

Microstructural characterization of gas-pressure-sintered α -silicon nitride containing β -phase seeds

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Abstract

The starting α - Si_3N_4 powders with or without the addition of β -phase seeds using Y_2O_3 and Al_2O_3 as sintering aids were gas-pressure-sintered with the conditions, 0.9 MPa nitrogen gas at 1850 °C for 1 h. The microscopic evidence indicates that β - Si_3N_4 seeds incorporated in the starting α - Si_3N_4 powders play an important role in microstructural development and mechanical properties for silicon nitride. The growth of β - Si_3N_4 grains is initiated from the seeds, resulting in a core/shell microstructure was observed in the abnormal grain growth. As a result, the fracture toughness of silicon nitride was improved from 5.5 to 7.6 MPa m^{1/2} by adding β -phase seeds.

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1. Introduction

Silicon nitride is an attractive ceramic material because of its excellent mechanical properties at both ambient and elevated temperatures. Therefore, it has been widely used for structural applications, such as cutting tools, mechanical sealing, bearings, heat exchangers, components for heat engines and in chemically corrosive environments [1,2]. The high fracture toughness that is observed in silicon nitride ceramics is attributed to the needlelike grain morphologies that are evidenced in the microstructure. Tailoring of the Si_3N_4 microstructure is possible via the inclusion of β - Si_3N_4 seeds in the initial sintering composition [3]. The β - Si_3N_4 powder was gas-pressure sintered at 2000 °C for 2–8 h in 30 MPa nitrogen gas. These materials had a microstructure of “in-situ composites” as a result of exaggerated grain growth of some β - Si_3N_4 grains during firing [4]. Typical fracture toughness values of silicon nitrides obtained by pressureless sintering are in the range of 4–6 MPa m^{1/2}. By seeding morphological regulated particles, fracture toughness of silicon nitride was improved from 6.3 to 8.4–8.7 MPa m^{1/2}, retaining high strength levels of about 1 GPa [5]. Kleebe et al., reported on the effect of grain

boundary phase. The grain-boundary microstructure and interface chemistry of $\text{Yb}_2\text{O}_3/\text{Al}_2\text{O}_3$ fluxed sintered Si_3N_4 materials with and without the addition of CaO has effected the grain boundary width [6]. The amorphous phase of grain boundary still limited material properties such as mechanical strength, creep resistance, thermal conductivity and high temperature properties. The α - β transformation of silicon nitride has occurred in presence of a liquid phase and the solution-precipitation mechanism dominant [7]. The incorporated β - Si_3N_4 seeds played an essential role in the heterogeneous grain growth of β - Si_3N_4 grains and clearly observed the core/shell structure [8].

In this study, we investigated the effect of addition β - Si_3N_4 seeds. Image analysis, transmission electron microscopy (TEM) and scanning electron microscopy (SEM) were using for analyzing the effect of β - Si_3N_4 seeds on the microstructure. The flexural strength and fracture toughness were also investigated.

2. Experimental procedure

2.1. Materials fabrication

The Si_3N_4 (UBE SN-E10) powder was mixed with 2 wt.% Al_2O_3 (16SG, Alcoa, USA, 0.5 μm), 6 wt.% Y_2O_3

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(5603, Molycorp, USA, 1.8 μm) and the $\beta\text{-Si}_3\text{N}_4$ (Cerac; S-1177, 0.74 μm) in a polyurethane bottle with high-purity silicon nitride balls and ethanol for 24 h. The ratio of ball, charge and vehicle was 6:1:5 in weight. It was dried in a rotary evaporator. Dried agglomerates were ground with a mortar and pestle, and passed through a 200 meshes sieve to pulverize aggregates. Samples were gas-pressure sintered with the conditions, 0.9 MPa nitrogen gas at 1850 $^{\circ}\text{C}$ for 1 h in a graphite furnace (Fuji Dempa High Multi 5000).

2.2. Microstructural analysis

Flexural strength was measured by a four-point bending test on a universal testing machine (Instron 8511) at a loading rate of 0.5 mm/min. Testing samples were machined into bars with dimensions of 3.5 \times 4.5 \times 45 mm and polished to 15 μm . The inner and outer spans used were 20 and 40 mm, respectively. Fracture toughness was measured following the derivation of Evans and Charles [9] by the indentation technique.

TEM foil preparation was performed by standard techniques which include diamond cutting, ultra-sound drilling, mechanical grinding, dimpling, ion thinning to

perforation, and a light carbon coating. An energy dispersive spectrometer (EDS) associated with TEM was employed for elemental analysis, and high resolution electron microscopy (HREM) images were taken (Model: Jeol-3010) operating at 300 kv. A scanning electron microscope (Hitachi S-4100) was employed to examine the microstructure. Some samples were plasma etched (Plasma-Them Inc., Series 70) in gas mixtures of CF_4 and O_2 with a flow ratio of 93:7 in RF sputtering system for 2 min and then ultrasonically cleaned prior to examination by SEM. The size distribution of grains was measured by an image analyzer associated with OPTIMAS (Bioscan Inc., Edmonds, Washington USA) and was calculated following the statistical derivation by Woetting et al. [10].

3. Results and discussion

Typical SEM micrographs of Si_3N_4 containing different amount of $\beta\text{-Si}_3\text{N}_4$ seeds are shown in Fig. 1. Samples had a compound microstructure composed of small matrix grains and large elongated grains. As revealed by Fig. 1(b–d), the number of large grains increases con-

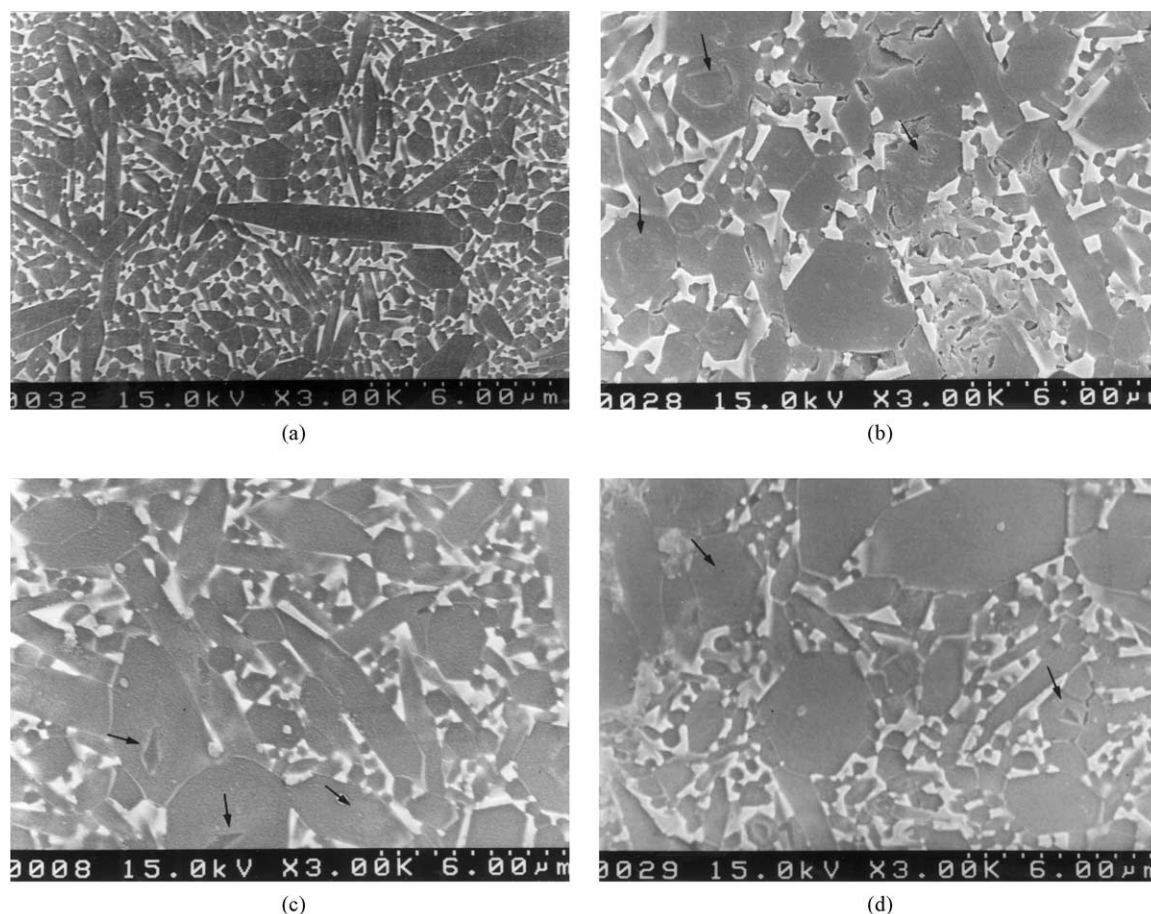


Fig. 1. Microstructure of Si_3N_4 ceramics with (a) 0 wt.% $\beta\text{-Si}_3\text{N}_4$, (b) 2 wt.% $\beta\text{-Si}_3\text{N}_4$, (c) 5 wt.% $\beta\text{-Si}_3\text{N}_4$, and (d) 7 wt.% $\beta\text{-Si}_3\text{N}_4$. Samples were sintered at 0.9 MPa nitrogen gas at 1850 $^{\circ}\text{C}$ for 1 h.

sistently with a small amount of seeds. These sintered samples also showed bimodal microstructure with large grains in the fine matrix grains. The average grain diameters of β - Si_3N_4 indicate a trend of increase in grain size with the amount of seeds. These results are shown in Fig. 2. With seed grain size distribution patterns were complex which compared without seed of the sintered samples. Emoto et al. [11] reported, the grain growth of α - Si_3N_4 is through the solution process of liquid phase sintering and subsequent precipitation of β -phase in additive β - Si_3N_4 seeds. These seeds should act as nuclei for grain growth. It was formerly discussed that a large diameter and elongated grains exhibit a core/rim structure, in which the growth of β -grains is initiated from the β -seeds [8]. Hirosaki et al. [12] have proposed that the elongated grains in the materials with seeds had a larger diameter and a smaller aspect ratio

than without seeds. A core/rim structure was observed in the elongated grains.

The flexural strength slightly decreased with addition β -phase seeds, because of the large elongated grains in the matrix possibly being effected. Fracture toughness progressively increases with the addition of β - Si_3N_4 seeds, as shown in Fig. 3, from $5.5 \text{ MPa}^{1/2}$ for without seeds Si_3N_4 , to between 6.5 and $7.5 \text{ MPa}^{1/2}$ for 7 wt.% β - Si_3N_4 seeds. The elongated grains of β - Si_3N_4 can be formed in situ reinforced monolithic silicon nitride. Becher et al. [13] have proposed that with the addition of 2% rodlike seeds, the fracture resistance can be increased due to bimodal grain diameter distribution. However, a larger amount seeds gave improvement in fracture toughness. The increased fracture toughness may be related to the bimodal microstructure, which is ascribed to grain bridging and crack deflection. Faber et

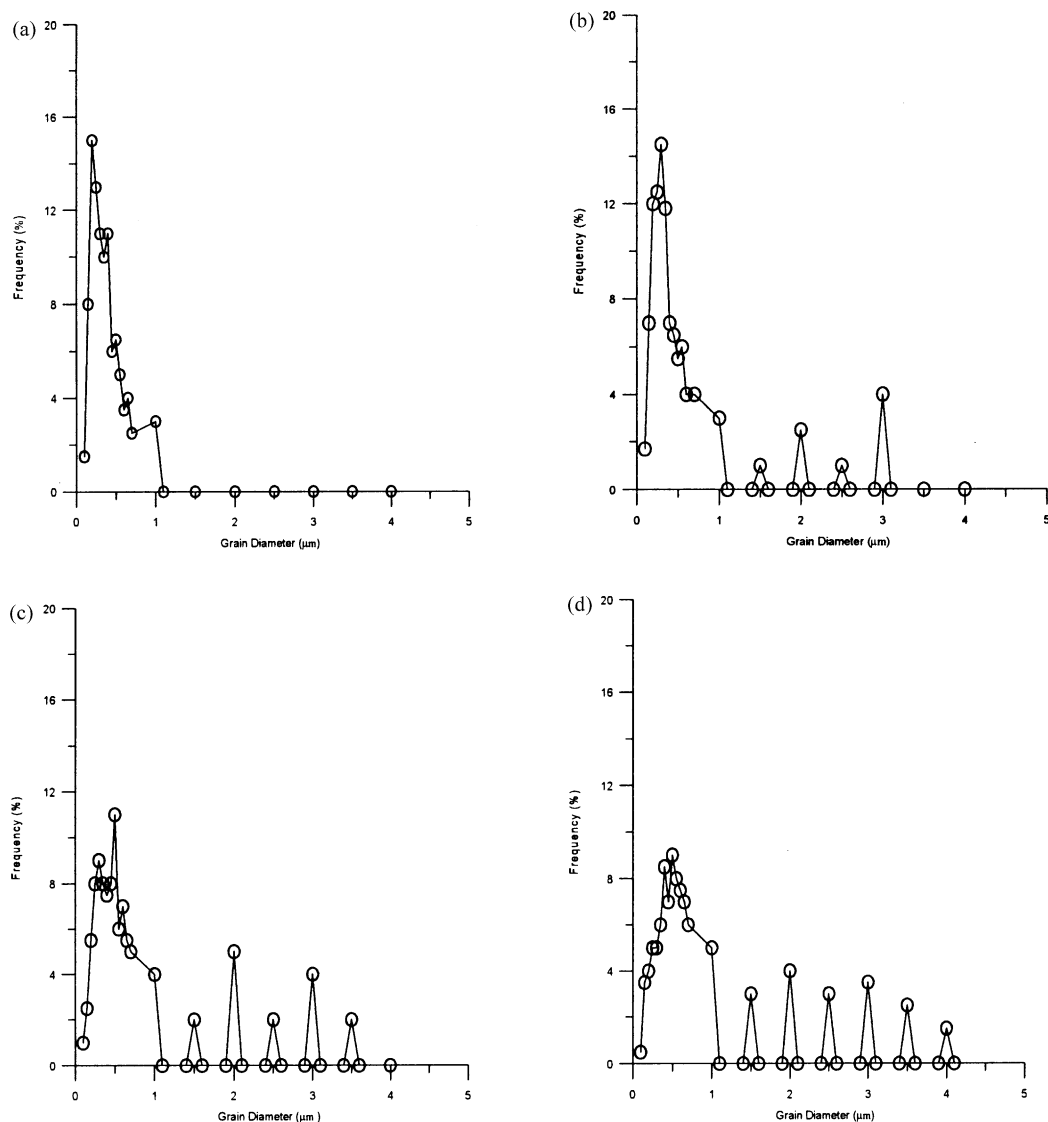


Fig. 2. Grain diameter distribution of Si_3N_4 containing different amount of β - Si_3N_4 : (a) 0 wt.% seed, (b) 2 wt.% seed, (c) 5 wt.% seed, (d) 7 wt.% seed. Samples were sintered at 0.9 MPa nitrogen gas at 1850°C for 1 h.

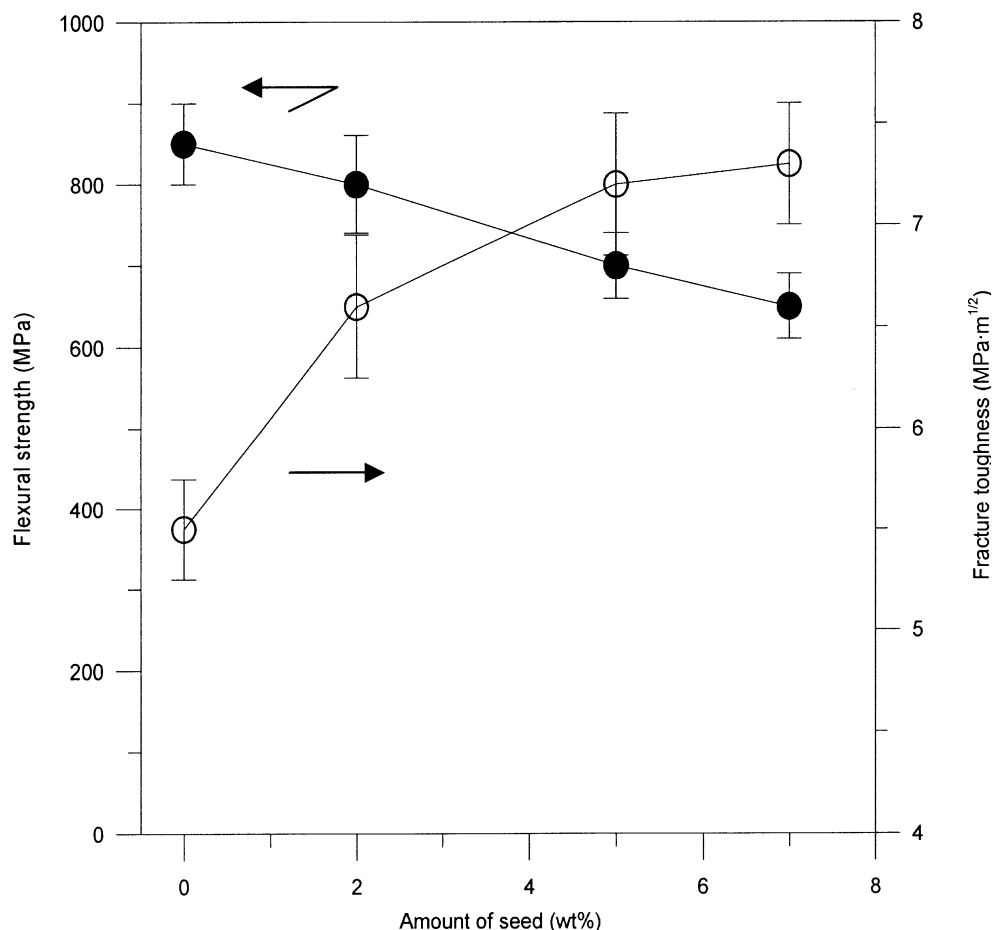


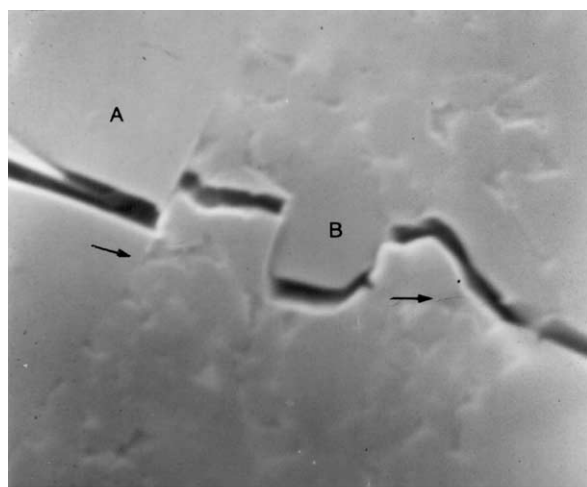
Fig. 3. Mechanical properties of silicon nitride sintered at 1850 °C for 1 h as a function of amounts of β -seed.

al. [14] have reported that the fracture toughness increased due to crack deflection around second phase particles. The most effective morphology for deflecting propagating cracks in the rod of high ratio. Ohashi et al. [15] Pointed out that the intergranular fracture of liquid phase sintered ceramics is dependent on the thermal residual stress in the vicinity of the intergranular phase.

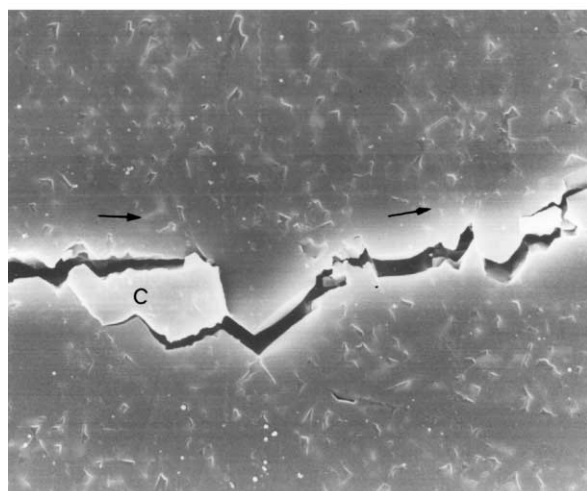
SEM analysis showed that those with seeds have a bimodal microstructure and large columnar grains, i.e., coarse elongated grains within a fine grain matrix. Observation of the Vickers indentation crack introduced on a polished surface revealed that the crack was deflected by β - Si_3N_4 columnar particles. Fig. 4 shows the travel of a Vickers indentation crack. It is clear that the crack traveled around the β - Si_3N_4 grains, which the crack deflected and branched at points “B” and “C”. However, this is clear evidence of crack deflection so that more energy is absorbed during fracture of the β - Si_3N_4 columnar grains. It was suggested that the crack propagation resistance is increased by both the crack deflection and bridging dominant. This finding is consistent with results reported by Kleebe et al., who indicate that the toughening contribution from crack bridging strongly

increases with an increase in larger elongated β - Si_3N_4 grains [16].

Fig. 5(a) shows the sintered sample, the amorphous film had a constant thickness along the entire grain boundary and in triple-grain junctions. For structural analysis of the amorphous, it has been reported that the average film thickness was 0.99 nm with a standard deviation of ± 0.1 nm [17]. The reduction in strength is due to softening at elevated temperature. On the other hand, the high resolution TEM image of the core/shell interface is shown in Fig. 5(b). The lattice image indicates that the core and shell do not have an amorphous phase in the interface. The lattice planes suggested a coherence between the core and the shell, which showed the same orientation and degree. The separation of the lattice planes was 0.659 nm, corresponding to a (100) plane of β - Si_3N_4 . The core is a β - Si_3N_4 seed, which acts as a nucleus during liquid phase sintering. The aluminum concentration in the core was apparently much greater than that in the shell [18]. The dark contrast and lattice fringe shift at the core/rim boundary were attributed to an elastic strain caused by a mismatch of the lattice spacing [13].



(a) 3μm

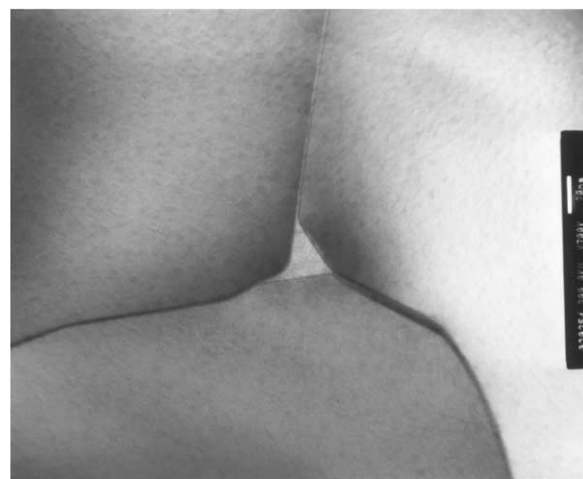


(b) 6μm

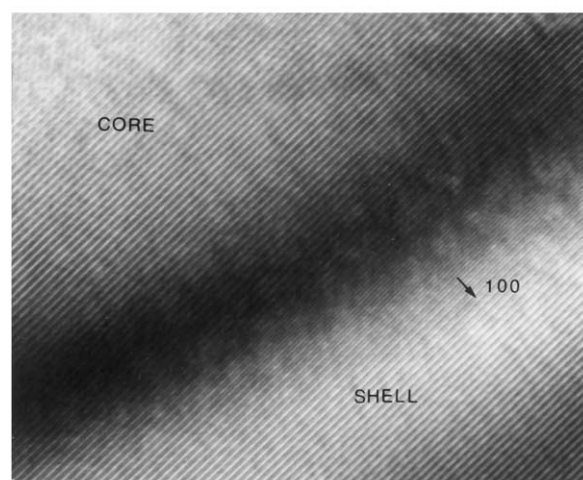
Fig. 4. SEM micrographs of Vickers indentation crack propagation paths with 2 wt.% seeds: (a) cracking bridging and (b) crack branching.

4. Conclusion

1. The SEM micrograph shows that improvement of fracture toughness was directly related to the bimodal microstructure with large grains in the fine matrix grains, which arose from crack bridging and deflection interaction. This crack deflection mechanism played an important role in the toughening effects.
2. The average grain diameters of β - Si_3N_4 indicate a trend of increase in grain size with the amount of seeds.
3. The grain-boundary amorphous film was shown along the entire grain boundary and in triple-grain junctions.
4. The lattice image shows a coherence match between the core and the shell boundary.



(a)



(b) 5nm

Fig. 5. TEM lattice image of silicon nitride showing (a) grain-boundary amorphous phase, and (b) lattice image of the core and shell structure.

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